# AUDIO PROCESSING SCHEMATIC

241 242 243 244 245 246 247 248 249 250 251 252 253 254 255 256 257 258 259 260

A B C D E F G H I J K L

U11701

U11702

U11801

PART OF U11490

PART OF U11490

Q11540 Q11499 Q11498 Q11701 Q11702 Q11801

FROM TRUS

FROM R_AUD

FROM L_AUD

TO FAV_HEAD_L

TO FAV_HEAD_R

PA_R

PA_L

TO PA_R

TO PA_L

J11801

TO J24901

FROM SUB_DET

FROM SUB_CONT

FROM FAST_MUTE

DACQ_I2C_DAT <5.39-I>

DACQ_I2C_CLK <5.38-I>

ALL INTEGRATED CIRCUITS AND MANY OTHER SEMICONDUCTORS ARE ELECTROSTATICALLY SENSITIVE AND REQUIRE SPECIAL HANDLING TECHNIQUES DESCRIBED UNDER "ELECTROSTATICALLY SENSITIVE (ES) DEVICES" IN THE SAFETY AND SERVICING PRECAUTIONS PUBLICATION.

PRODUCT SAFETY NOTE

COMPONENTS WITH A ⚠ HAVE SPECIAL CHARACTERISTICS IMPORTANT TO SAFETY. BEFORE REPLACING ANY OF THESE COMPONENTS READ CAREFULLY THE PRODUCT SAFETY NOTICE IN THIS SERVICE DATA. DO NOT DEGRADE THE SAFETY OF THE SET THROUGH IMPROPER SERVICING.

SCHEMATIC NOTES

1. RESISTANCE VALUES ARE IN OHMS; K=X1000, Meg=X1,000,000.
   RESISTORS ARE 1/4W 5%, EXCEPT WHERE INDICATED.
   [ ] INDICATES FLAT MAXI-CHIP COMPONENT. 1/8W EXCEPT WHERE INDICATED.
   / \ INDICATES FLAT MINI-CHIP COMPONENT. 1/16W EXCEPT WHERE INDICATED.
2. CAPACITANCE VALUES 1.0 AND ABOVE ARE IN pF. VALUES BELOW 1.0 ARE IN µF EXCEPT WHERE INDICATED. VOLTAGE RATING IS 50V EXCEPT WHERE INDICATED.
   [ ] INDICATES FLAT MAXI-CHIP COMPONENT.
   / \ INDICATES FLAT MINI-CHIP COMPONENT.
3. ⏚ DENOTES CHASSIS GROUND. ⊗ INDICATES CONNECTION VIA POINT-TO-POINT WIRE.
   ⌒ -INDICATES JUMPER WIRE.
   ⊶ -INDICATES ZERO OHM CHIP COMPONENT.



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